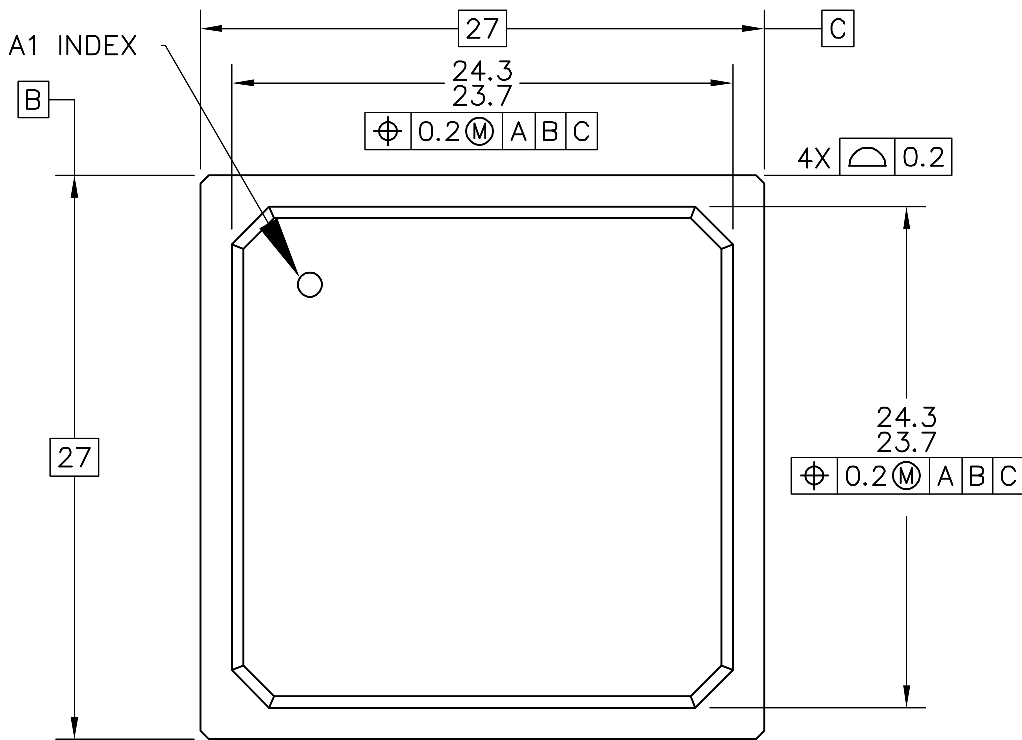

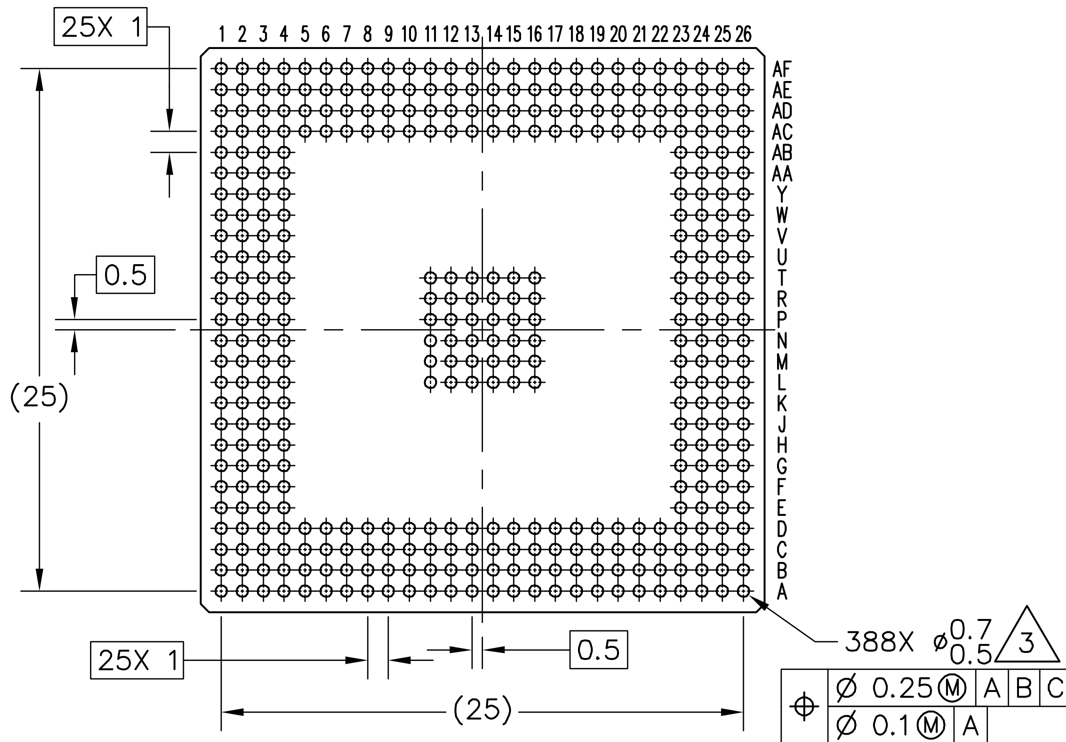

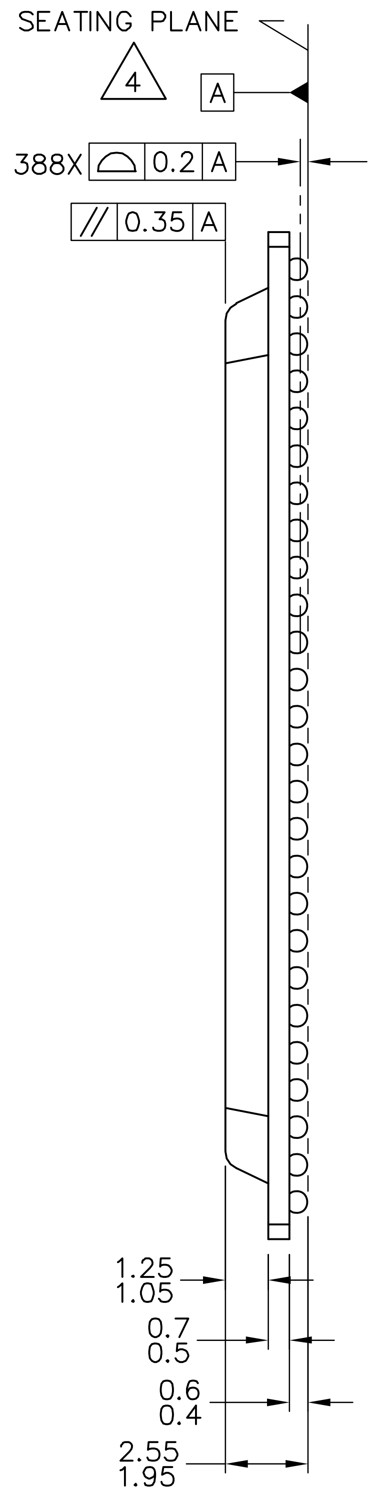

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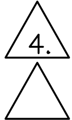
	CASE NUMBER: 1164–02	25 JAN 2007
	STANDARD: JEDEC MS–034 AAL–1	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.



4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PACKAGE CODES:
   5254 – 2 LAYER SUBSTRATE PACKAGE
   5367 – 4 LAYER SUBSTRATE PACKAGE

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